



2024-25 John Ries Scholarship

The Expanded Shale, Clay, and Slate Institute (ESCSI) is pleased to announce the **John Ries Scholarship** in Academic Year 2024-25 for undergraduate and graduate students in **civil engineering** or closely related majors.

The ESCSI is the international trade association for manufacturers of rotary kiln-produced expanded shale, expanded clay and expanded slate (ESCS) lightweight aggregate. ESCSI promotes the extensive use of rotary kiln-produced lightweight aggregate in the lightweight concrete masonry and structural lightweight concrete markets, as well as use in asphalt, geotechnical and other applications. Based on research and development, educational material is disseminated to all phases of the construction industry. The association works closely with other technical organizations, such as ACI and ASTM, to maintain product quality, life-safety and professional integrity throughout the construction industry and related building code bodies.

Applications are accepted as self-nominations by undergraduate or graduate students in civil engineering or closely related majors who are enrolled in fall 2024 and will return to school for spring 2025. All applications shall be postmarked no later than **December 1, 2024**. Applications should include the following items:

1. The application form signed by the applicant (electronic signature is acceptable);
2. A one-page statement of qualifications by student describing motivation in ESCS materials; academic and career goals related to ESCS applications; planned research- or practice-based projects involving ESCS materials; and/or the value of this scholarship to achieve goals or complete projects (letter-size, single-spaced, 1" margin, font size 12, doc or pdf);
3. Unofficial transcripts indicating the current GPA of 2.75 or higher (pdf);
4. A confidential letter of recommendation by a faculty; signed, dated, and sealed; or sent directly via email to ESCSI by the faculty with the subject "John Ries Scholarship".

Please send completed application and attachments, as well as any question to following address and mentioning "John Ries Scholarship" in the subject line of emails, or back of mail packages:

Expanded Shale, Clay and Slate Institute
35 East Wacker Dr., Suite 850
Chicago, IL 60601
info@escsi.org



**EXPANDED SHALE, CLAY
& SLATE INSTITUTE**

Rotary Kin Structural Lightweight Aggregate

John Ries Scholarship Application

Due before December 1, 2024

Applicant must be a current undergraduate or graduate student in civil engineering or a closely related major for AY 2024-25. The scholarship is \$5,000 for one student. The scholarship will be awarded in person by an ESCSI representative and will be announced on the ESCSI web and social media. An online application is available at <https://forms.gle/sgxRQrUEVkj3ZD8A>.

Applicant First _____ M _____ Last _____

Expected Degree BS _____ MS _____ Ph.D. _____ Other (Write) _____

Area of Study Civil Engineering _____ Other (Write) _____

Year of Study Begin _____ Expected Graduation _____

University Name _____ City _____ State _____

Contact Information Mailing Address _____

Phone _____ email _____

Referenced Faculty Name _____ Title _____

Department _____ email _____

Applicant's Signature _____ Date _____

Contact Information:

Expanded Shale, Clay and Slate Institute
35 East Wacker Dr., Suite 850
Chicago, IL 60601
info@escsi.org

Checklist: 1) Application ; 2) Statement ; 3) Transcripts ; 4) Letter of Recommendation .